



Advanced Thermal Management of Integrated Electronic Devices

Guest Editors:

Dr. Bin Xie

School of Mechanical Science
and Engineering, Huazhong
University of Science and
Technology, Wuhan 430074,
China

Dr. Bofeng Shang

School of Physics, Zhengzhou
University, Zhengzhou 450001,
China

Deadline for manuscript
submissions:

closed (15 December 2023)

Message from the Guest Editors

Dear Colleagues,

With the rising power density and ever-shrinking size of electronic devices, thermal issues related to the high junction temperature of chips are becoming rather severe. Thermal management is essential for boosting both the performance and stability of integrated electronic devices.

This Special Issue is intended to present research papers and review articles that report on the recent advances in thermal management of integrated electronic devices, including thermal materials, heat dissipation system designs, thermal characterizations, thermal transport analysis, and thermal modeling. The topics covered in this Special Issue include, but are not limited to:

- Emerging thermal interfacial materials
- Advanced thermal characterization techniques
- New concepts in thermal management of electronic devices
- Forced air and liquid cooling techniques
- Phase change materials
- Thermal modeling and simulations
- Thermal reliability analysis of integrated electronic devices
- Chip-level thermal management
- Liquid Metal and its system design
- Energy conversion and management

You are welcome to contribute!!!





an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Flavio Canavero

Department of Electronics and
Telecommunications,
Politecnico di Torino, 10129
Torino, Italy

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), CAPlus / SciFinder, Inspec, and other databases.

Journal Rank: JCR - Q2 (*Physics, Applied*) / CiteScore - Q2 (*Control and Systems Engineering*)

Contact Us

Electronics Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/electronics
electronics@mdpi.com
[X@electronicsMDPI](https://x.com/electronicsMDPI)